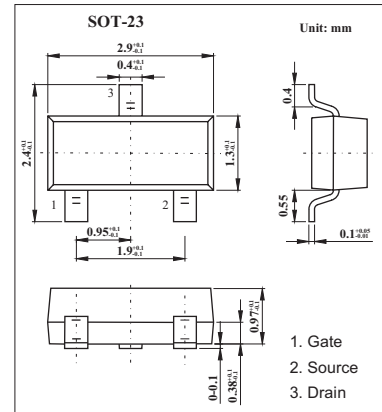
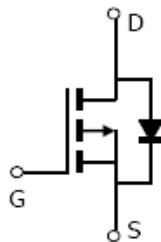


■ Features

- $V_{DS} (V) = 30V$
- $I_D = 5.8 A (V_{GS}=10V)$
- $R_{DS(ON)} < 28 m\Omega (V_{GS} = 10V)$
- $R_{DS(ON)} < 43 m\Omega (V_{GS} = 4.5V)$



■ Absolute Maximum Ratings  $T_a = 25^\circ C$

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DS}$	30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current *1 $T_A=25^\circ C$	$I_D$	5.8	A
Current *1 $T_A=70^\circ C$		4.9	
Pulsed Drain Current *2	$I_{DM}$	20	
Power Dissipation *1 $T_A=25^\circ C$	$P_D$	1.4	W
$T_A=70^\circ C$		1	
Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	$^\circ C$

\*1The value of  $R_{\theta JA}$  is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz.

Copper, in a still air environment with  $T_A = 25^\circ C$

\*2 Repetitive rating, pulse width limited by junction temperature.

■ Thermal Characteristics

Parameter		Symbol	Typ	Max	Unit
Maximum Junction-to-Ambient*1	$t \leq 10s$	$R_{\theta JA}$	65	90	$^\circ C/W$
Maximum Junction-to-Ambient *1	Steady-State		85	125	$^\circ C/W$
Maximum Junction-to-Lead *2	Steady-State	$R_{\theta JL}$	43	60	$^\circ C/W$

\*1The value of  $R_{\theta JA}$  is measured with the device mounted on 1in<sup>2</sup> FR-4 board with 2oz.

Copper, in a still air environment with  $T_A = 25^\circ C$

\*2 . The  $R_{\theta JA}$  is the sum of the thermal impedance from junction to lead  $R_{\theta JL}$  and lead to ambient.

■ Electrical Characteristics Ta = 25°C

Parameter	Symbol	Testconditons	Min	Typ	Max	Unit	
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	I <sub>D</sub> =250 μ A, V <sub>GS</sub> =0V	30			V	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =24V, V <sub>GS</sub> =0V			1	μ A	
		V <sub>DS</sub> =24V, V <sub>GS</sub> =0V, T <sub>J</sub> =55°C			5		
Gate-Body leakage current	I <sub>GSS</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =±20V			100	nA	
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> I <sub>D</sub> =250 μ A	1	1.9	3	V	
On state drain current	I <sub>D(ON)</sub>	V <sub>GS</sub> =4.5V, V <sub>DS</sub> =5V	20			A	
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =5.8A		22.5	28	mΩ	
		V <sub>GS</sub> =10V, I <sub>D</sub> =5.8A T <sub>J</sub> =125°C		31.3	38		
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =5.0A		34.5	43	mΩ	
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =5V, I <sub>D</sub> =5.8A	10	14.5		S	
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> =1A		0.76	1	V	
Maximum Body-Diode Continuous Current	I <sub>S</sub>				2.5	A	
Reverse Transfer Capacitance	C <sub>iss</sub>			680	820	pF	
Gate resistance	C <sub>oss</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> =15V, f=1MHz		102		pF	
Input Capacitance	C <sub>rss</sub>			77		pF	
Output Capacitance	R <sub>g</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, f=1MHz		3	3.6	Ω	
Total Gate Charge (10V)	Q <sub>g</sub>	V <sub>GS</sub> =10V, V <sub>DS</sub> =15V, I <sub>D</sub> =5.8A		13.88	17	nC	
Total Gate Charge (4.5V)	Q <sub>g</sub>			6.78	8.1	nC	
Gate Source Charge	Q <sub>gs</sub>			1.8		nC	
Gate Drain Charge	Q <sub>gd</sub>			3.12		nC	
Turn-On Rise Time	t <sub>D(on)</sub>				4.6	6.5	ns
Turn-Off DelayTime	t <sub>r</sub>	V <sub>GS</sub> =10V, V <sub>DS</sub> =15V, R <sub>L</sub> =2.7 Ω, R <sub>GEN</sub> =3 Ω		3.8	5.7	ns	
Turn-Off Fall Time	t <sub>D(off)</sub>			20.9	30	ns	
Turn-On DelayTime	t <sub>f</sub>				5	7.5	ns
Body Diode Reverse Recovery Time	t <sub>rr</sub>		I <sub>F</sub> =5.8A, di/dt=100A/μ s		16.1	21	ns
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	I <sub>F</sub> =5.8A, di/dt=100A/μ s		7.4	10	nC	

■ Marking

Marking	A4
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